

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

<b>PCN Title:</b>	Manufacturing fabrication process and wafer size changes (6-to-8 inch) for ADI products in current S3EIWK process (to new B3EIWK 8-inch)
<b>Publication Date:</b>	21-Feb-2023
<b>Effectivity Date:</b>	26-May-2023 <i>(the earliest date that a customer could expect to receive changed material)</i>
<b>Revision Description:</b>	

**Description Of Change:**

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 ADI products in current wafer fabrication process S3EIWK (6-inch wafer size) at ADI's Beaverton/Oregon foundry (ADBN)

**Reason For Change:**

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 Due to tool capacity constraint for the 6-inch S3EIWK process, ADI is moving to the 8-inch B3EIWK process to ensure adequate capacity for supply continuity and long term sustainability.  
 ADI has achieved equivalency between the two processes.  
 B3EIWK process reliability qualification report is attached (MFN\_B3 Qual report)  
 The wafer fabrication location remains the same.

The Form/Fit/Function of the devices is unchanged.

**Impact of the change (positive or negative) on fit, form, function & reliability:**

**Product Identification (this section will describe how to identify the changed material):**

**Summary of Supporting Information:**

**Supporting Documents:**

**ADI Contact Information:**

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

**Appendix A - Impacted items, see csv PN listing in PCN Zip file**